

**Amendments to the Claims:**

*This listing of claims replaces all prior versions and listing of claims in the application.*

1. (Currently amended) A semiconductor fabrication vaporizer ~~Vaporizer for vaporizing a liquid source, the vaporizer comprising:~~
  - ~~- a liquid source supplying part 10 for supplying a liquid source;~~
  - ~~- a vaporizing part 30 for vaporizing the liquid source; and~~
  - ~~- an O-ring [[17]] positioned on a place in which the liquid source supplying part 10 and the vaporizing part [[30]] are in contact with each other so as to and minimize a thermal contact area between for the liquid source supplying part 10 and the vaporizing part [[30]].~~
2. (Currently amended) A semiconductor fabrication vaporizer ~~Vaporizer for vaporizing a liquid source, the vaporizer comprising:~~
  - ~~- a liquid source supplying part 10;~~
  - ~~- a vaporizing part [[30]];~~
  - ~~- a recess [[16]];~~
  - ~~- an O-ring a-O-ring 17;~~

    said liquid source supplying part including a source intake ~~intaking~~ passage 11 for receiving a liquid source, an intake ~~intaking~~ tube [[12]] communicated with the source intake ~~intaking~~ passage [[11]] and having a fine hole [[12a]] formed thereon, a stopper surface [[13]] formed on a place at which the source intake ~~intaking~~ passage [[11]] and the intake ~~intaking~~ tube [[12]] are joined together, an adjusting pin 14 for controlling supplying of the to control a liquid source at a location between [[from]] the source intake ~~intaking~~ passage [[11 to]] and the intake ~~intaking~~ tube [[12]], and a diaphragm [[15]] integral with the adjusting pin [[14]];

    said vaporizing part [[30]] having a body and including a first heater [[31]]

attached to a body the body of the vaporizing part 30 to heat the vaporizing part, a vaporizing chamber 35 ~~for vaporizing the liquid source~~, a gas transport transporting passage 37 ~~for supplying a transporting gas~~, and a discharge discharging port 38 ~~for communicating with the vaporizing chamber 35 and for discharging to discharge the transporting a transported gas and the vaporized liquid source to [[the]] an area~~ outside of the vaporizing chamber [[35]], and

said recess [[16]] being formed on a selected one of the liquid source supplying part 10 ~~and or~~ the vaporizing part [[30]] to minimize a thermal contact area therebetween, and coupled with the O-ring 17.

3. (Currently amended) The semiconductor fabrication vaporizer as claimed in claim 2, wherein the diaphragm has a lower surface and wherein the lower surface of the diaphragm [[15]] is formed as a part of a supply the supplying line for the liquid source and is formed by the source intake intaking passage [[11]].
4. (Currently amended) The semiconductor fabrication vaporizer as claimed in claim 2, wherein the diaphragm has a lower surface and wherein the lower surface of the diaphragm 45 is separated from a supply the supplying line for the liquid source and is formed by the source intake intaking passage [[11]].
5. (Currently amended) The semiconductor fabrication vaporizer as claimed in claim 2, wherein the adjusting pin has an upper side and further comprising an actuator [[50]] adjacent to the upper side of the adjusting pin [[14]], and wherein the adjusting pin [[14]] is operated by the actuator.
6. (Currently amended) The semiconductor fabrication vaporizer as claimed in claim 2, wherein the vaporizing part [[30]] further comprises a second heater [[32]], the second heater being formed to protrude into the vaporizing chamber [[35]].

7. (Currently amended) The semiconductor fabrication vaporizer as claimed in claim 1, and further comprising an adjusting pin to control a liquid source, having at least one end, and a stopper surface, and wherein one end of the adjusting pin [[14]] is inclined at an first inclined angle and the stopper 13 has an has an corresponding inclined part[[, the]] having [[an]] a second inclined angle, and wherein the first inclined angle of the adjusting pin is smaller than [[that]] the second inclined angle of the stopper surface.
8. (Currently amended) The semiconductor fabrication vaporizer as claimed in claim 2, wherein the vaporizing chamber has an upper inner circumference, and wherein the gas transport passage transporting part 37 is communicated with [[the]] a gap [[36]] formed between the upper inner circumference of the vaporizing chamber [[35]] and the intake intaking tube [[12]] of the liquid source supplying part 10.
9. (Currently amended) The semiconductor fabrication vaporizer as claimed in claim 6, wherein the first and the second heaters 31 and 32 include a temperature sensor 33 capable of sensing to sense a temperature of [[the]] a region in real time between the first heater [[31]] and the second heater [[32]] in real time.
10. (Currently amended) The semiconductor fabrication vaporizer as claimed in claim 6, wherein the first heater [[31]] and the second heater [[32]] are unified to form a heater block 57 mounted on the lower end of the heater block 57.
11. (Currently amended) The semiconductor fabrication vaporizer as claimed in claim 2, wherein the liquid source supplying part [[10]] further includes a cooling device 18 in order to cool heat transferred from the vaporizing chamber [[30]].
12. (Currently amended) The semiconductor fabrication vaporizer as claimed in claim 5, wherein the actuator [[50]] is any one selected from a manual actuator or a [[Piezo]] piezo actuator.

13. (Currently amended) The semiconductor fabrication vaporizer as claimed in claim 2, wherein the gas transport transporting passage [[37]] is inclined to increase a thermal contact area in order for the transporting gas to absorb a heat from with the vaporizing part chamber 30 enough.